



PART NO. : TG111-S12NYNRL

24PIN 0.039" LEAD PITCH SMT PACKAGE

DESIGNED FOR ONE-PORT GIGABIT, IEEE802.3ab OR
DUAL-PORT FAST ETHERNET, IEEE802.3u APPLICATIONS

COMPLIANT WITH IEEE802.3af REQUIREMENTS WITH
350mA CURRENT CARRYING CAPACITY FOR PoE

AUTO-MDIX COMPATIBLE

LEAD-FREE/RoHS COMPLIANT, "GREEN PRODUCT"

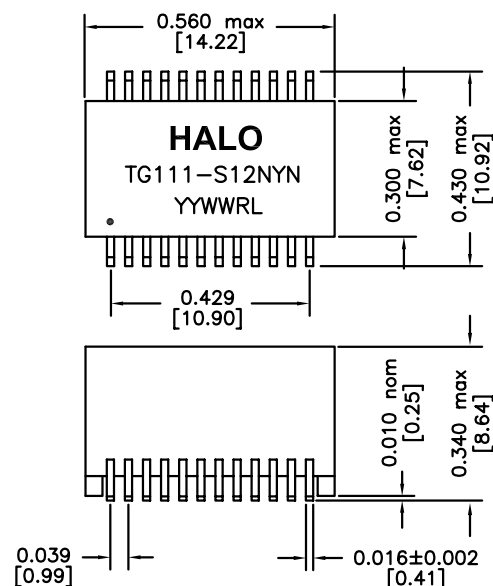
COMPATIBLE TO LEAD-FREE SOLDERING PROCESS
CONDITION PER IPC/JEDEC J-STD-020C

UL/EN60950 AND DEMKO RECOGNIZED

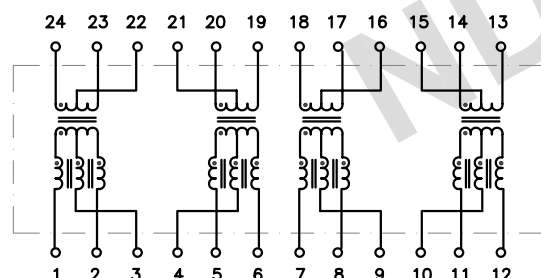
OPERATING TEMPERATURE 0/70°C

ELECTRICAL SPECIFICATIONS @ 25° C

URNS RATIO	1CT:1CT ±2%
OCL (100KHz,0.1Vrms,8mADC)	350μH min
INSERTION LOSS 1-100MHz	-1.1dB max
RETURN LOSS 1-40MHz	-18dB min
60MHz	-14dB min
80MHz	-12dB min
100MHz	-10dB min
CMR 1-100MHz	-40dB typ
CROSSTALK 1-30MHz	-50dB typ
60MHz	-45dB typ
100MHz	-40dB typ
ISOLATION	1,500Vrms



DIMENSIONS: Inch [mm]
CO-PLANARITY: 0.004 [0.10]
TOLERANCES: ±0.005 INCH IF NOT SPECIFIED



HALO/PBL

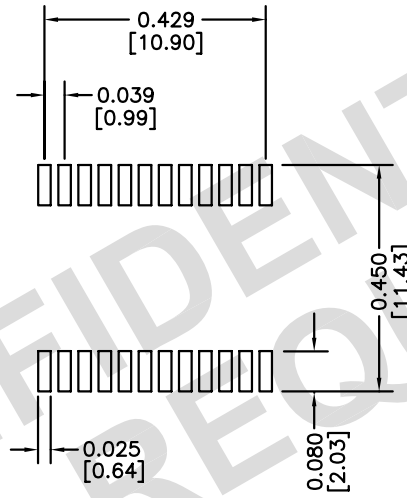
CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE	ISOLATION MODULE
FOR	FAST/GIGABIT ETHERNET
PART NO.	TG111-S12NYNRL
SCALE	NONE

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SIGNATURES	DATE	REV.	DESC.	DATE
DRAWN PETER LU	1/6/08	A	FIRST ISSUE	1/6/08
CHECKED LEI KEONG	9/22/09	B	REV. PART NUMBER	6/1/09
APPROVED PETER LU	9/22/09	C	UPDATE	6/4/09
FILE S12NYNRL.DWG		D	PROD. RELEASE	9/22/09





RECOMMENDED SOLDER PAD DIMENSIONS
DIMENSIONS: Inch [mm]

HALO/PBL

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KOWLOON, HONG KONG
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